- SDLS150 MARCH 1974 REVISED MARCH 1988
- Fast Multiplication . . . 5-Bit Product in 26 ns Typ
- Power Dissipation . . . 110 mW Typical
- Latch Outputs for Synchronous Operation
- Expandable for m-Bit-by-n-Bit Applications
- Fully Compatible with Most TTL and Other Saturated Low-Level Logic Families
- Diode-Clamped Inputs Simplify System Design

description

These low-power Schottky circuits are designed to be used in parallel multiplication applications. They perform binary multiplication in two's-complement form, two bits at a time.

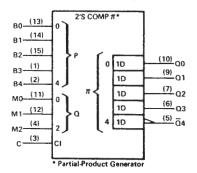
The M inputs are for the multiplier bits and the B inputs are for the multiplicand. The Q outputs represent the partial product as a recoded base-4 number. This recoding effectively reduces the Wallace-tree hardware requirements by a factor of two.

The outputs represent partial products in one'scomplement form generated as a result of multiplication. A simple rounding scheme using two additional gates is needed for each partial product to generate two's complement.

The leading (most-significant) bit of the product is inverted for ease in extending the sign to square (left justify) the partial-product bits.

The SN54LS261 is characterized for operation over the full military temperature range of -55° C to 125°C; the SN74LS261 for operation from 0°C to 70°C.

logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN54LS261	. J OR N	N PACKAGE
SN74LS261	. D OR	N PACKAGE
(TC	P VIEW)
B3 🗍	Uiel] Vcc
B4 [] 2] B2
	15	2
C ∐3	14] B1
<u>M2 []</u> 4	13	_ B0
Q4 [] 5	12	_ M1

11 **MO**

10 00

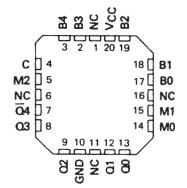
9 T Q1

O3 []6

02 🛛 7

GND 8

SN54LS261 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

		0	JTPU	TS				
LATCH CONTROL	MULTIPLIER			<u>0</u> 4	02	02	01	Q0
c	M2	M1	MO	4	03	αz	21	00
L	х	х	х	ā40	Q30	Q20	Q10	000
н	L	L	L	н	L	L	L	L
н	L	L	н	B4	B4	83	B2	B1
н	Ľ	н	L	B4	B4	83	B2	B1
н	L	н	н	B4	В3	B2	B1	BO
н	н	L	L	84	B3	B2	B1	Β̈́Ο
н	н	L	н	В4	B4	ВЗ	Ē2	₿1
н	н	н	L	84	B4	B3	<u>B</u> 2	B1
н	н	н	н	н	L	L	L	L

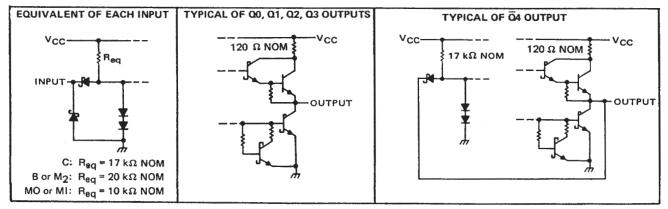
H = high level, L = low level, X = irrelevant

 $\overline{\rm Q4}_0\ldots {\rm Q0}_0$ = The logic level of the same output before the high-to-low transition of C.

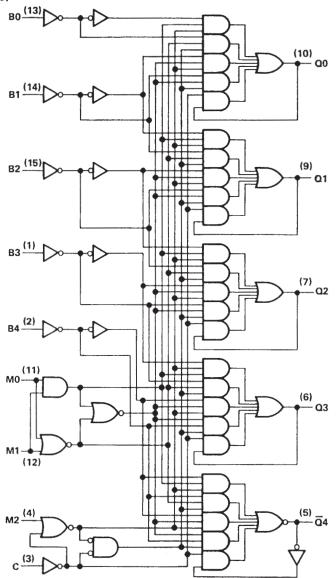
B4... B0 = The logic level of the indicated multiplicand (B) input.

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schematics of inputs and outputs



logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1) .		
		•••••••••••••••••••••••••••••••••••••
		$\cdot \cdot $
Storage temperature range	• • • • •	\cdot · · · · · · · · · · · · · · · · · · ·

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS261			SN74LS261				
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V	
High-level output current, IOH				-400			-400	μA	
Low-level output current, IOL				4			8	mA	
Width of enable pulse, t _W	· · · · · · · · · · · · · · · · · · ·	25			25			ns	
Setup time, t _{su}	Any M input	171			17∔			+	
	Any B input	15↓			15‡			ns	
Hold time, th	Any M input	01			01	· · · · · ·	_	+	
	Any B input	01			01			ns	
Operating free-air temperature, TA		-55		125	0		70	°C	

The arrow indicates that the falling edge of the enable pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]		SN54LS261			SN74LS261				
		TEST CONDITIONS.			MIN	TYP‡	MAX	MIN	τγρ‡	MAX	
VIH	High-level input voltage				2			2		***	V
VIL	Low-level input voltage						0.7			0.8	
VIK	Input clamp voltage	V _{CC} = MIN,	I _I =18 mA		1		-1.5	1		-1.5	
V _{OH}	High-level output voltage	V _{CC} = MIN, VIL = VIL max,	V _{IH} = 2 V, I _{OH} = -400 μ	A	2.5	3.4		2.7	3.4		v
Voi	Low-level output voltage	V _{CC} = MIN,	V _{IH} = 2 V,	1 _{OL} = 4 mA		0.25	0.4		0.25	0.4	
		VIL = VIL max		10L = 8 mA				1	0.35	0.5	V
I _L	Input current at	Vcc = MAX	Vi = 7 V	MO or MI			0.2	1		0.2	
	maximum input voltage		•1 • 7 •	All others			0.1			0.1	f mA
чн	High-level input current	Vcc = MAX,	V ₁ = 2.7 V	MO or MI			40			40	μA
			v - 2.7 v	All others			20			20	μ μ Α
41	Low-level input current	Vcc = MAX.	V1 = 0.4 V	MO or M1			-0.8			-0.8	mA
· I L.				All others			-0.4			-0.4	1
los	Short-circuit output current §	V _{CC} = MAX			-20		-100	20		-100	mA
lcc	Supply current	V _{CC} = MAX, Outputs open	All inputs at 0	ν,		20	38		20	40	mA

[†]For conditioning shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at $V_{CC} = 5 V$, $T_A = 25 °C$.

[§]Not more than one output should be shorted at a time and duration of the output short-circuit should not exceed one second.



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switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	MAX	UNIT
tPLH	с	Any Q			22	35	ns
tPHL	, c	Anya	0 15 -5		20	30	ns
tPLH	Any M input	Any Q	CL = 15 pF,		25	40	ns
^t PHL		Any C	RL = 2 kΩ, See Note 2		22	35	ns
^t PLH	Any B input	Any Q	See Note 2		27	42	ns
tPHL	HL Ally B linput Ally C				24	37	ns

 ¶ tp_{LH} = propagation delay time, low-to-high-level output; tp_{HL} = propagation delay time, high-to-low-level output NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

Multiplication of the numbers 26 (multiplicand) by 29 (multiplier) in decimal, binary, and 2-bit-at-a-time-binary is shown here:

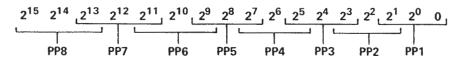
	DECIMAL	BINARY	2-BIT-AT-A-TIME BINARY
B M	26 29 234 52 754	Sign Bit 011010 011010 000000 011010 011010 011010 0101110010 01011110010 Sign Product Bit	01011110010

Two points should be noted in the two-bit-at-a-time-binary example above. First, in positioning the partial products beneath each other for final addition, each partial product is shifted two places to the left of the partial products above it instead of one place as is done in regular multiplication. Second, the msb of the partial product (the sign bit) is extended to the sign-bit column of the final answer.

A substantial reduction of multiplication time, cost, and power is obtained by implementing a parallel partial-product-generation scheme using a 2-bit-at-a-time algorithm, followed by a Wallace Tree summation.

Partial-product-generation rules of the algorithm are:

1. Examine two bits of multiplier M plus the next lower bit. For the first partial product (PP1) the next lower bit is zero.





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TYPICAL APPLICATION DATA

2. Generate partial product (PPi) as shown in the following table:

MULT	MULTIPLIER BITS FROM STEP 1			TO OBTAIN PARTIAL PRODUCT	
221-1	221-2	2 ²ⁱ⁻³	SYMBOL		
0	0	0	0	Replace multiplicand by zero	
0	0	1	+1 B	Copy multiplicand	
0	1	0	+1 B	Copy multiplicand	
0	1	1	+2 B	Shift multiplicand left one bit	
1	0	0	-2 B	Shift two's complement of multiplicand left one bit	
1	0	1	-1 B	Replace multiplicand by two's complement	
1	1	0	-1 B	Replace multiplicand by two's complement	
1	1	1	0	Replace multiplicand by zero	

3. Weight the partial products by indexing each two places left relative to the next-less-significant product.

4. Extend the most-significant bit of the partial product to the sign-bit place value of the final product.

EXAMPLE OF ALGORITHM

M = 29 = 011101	Operator Symbol	B = 26 = 011010
010 L	+1 B	00000011010
↓ 110	-1B	111100110
011	+2 B	0110100

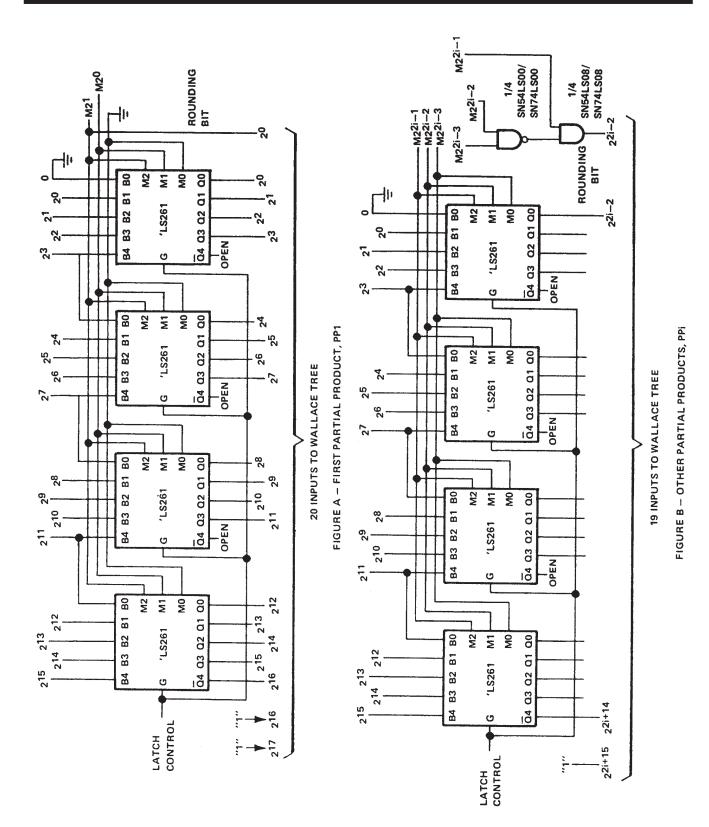
The summation of these partial products was shown in the 2-bit-at-a-time binary multiplication example above.

The 'LS261 generates partial products according to this algorithm with two exceptions:

- 1. The one's complement is generated for the cases requiring the two's complement. The two's complement can be obtained by adding one to the one's complement; this rounding can be done by using one NAND gate and one AND gate as shown in Figure B.
- 2. The most-significant bit is complemented to reduce the hardware required to extend the sign bit. This extension can be accomplished by adding a hard-wired logic 1 in bit position 2²ⁱ⁺¹⁵ of each partial product and also in bit position 2¹⁶ of the first partial product (PP1).

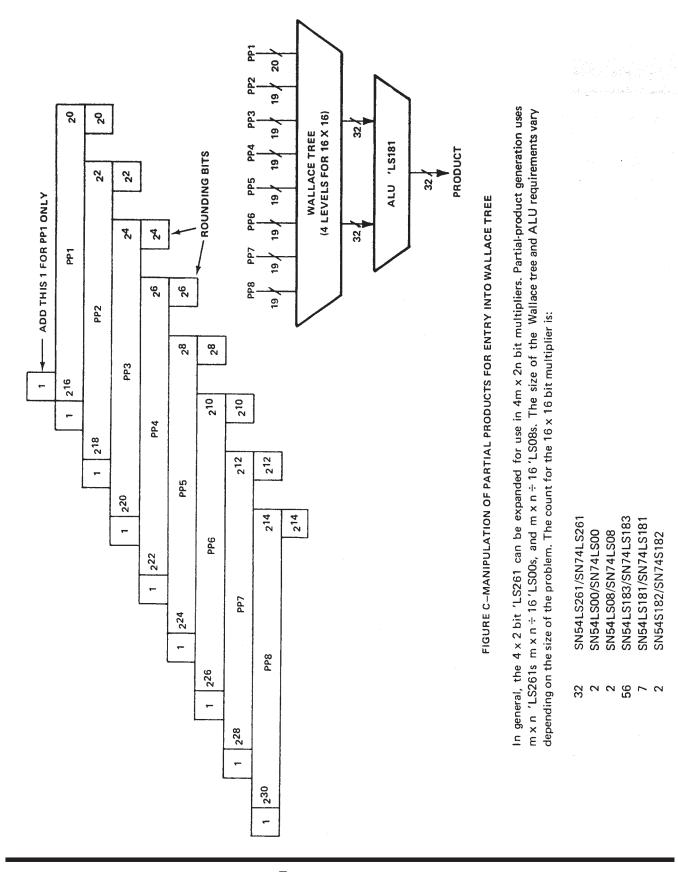


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